

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Somenath Mitra et al.

Application No.: 10/735,989

Group Art Unit: 3742

Examiner: Fastovsky, Leonid

Filing Date: December 15, 2003

Docket No: 436/12

For: MICROMACHINED HEATERS FOR

MICROFLUIDIC DEVICES

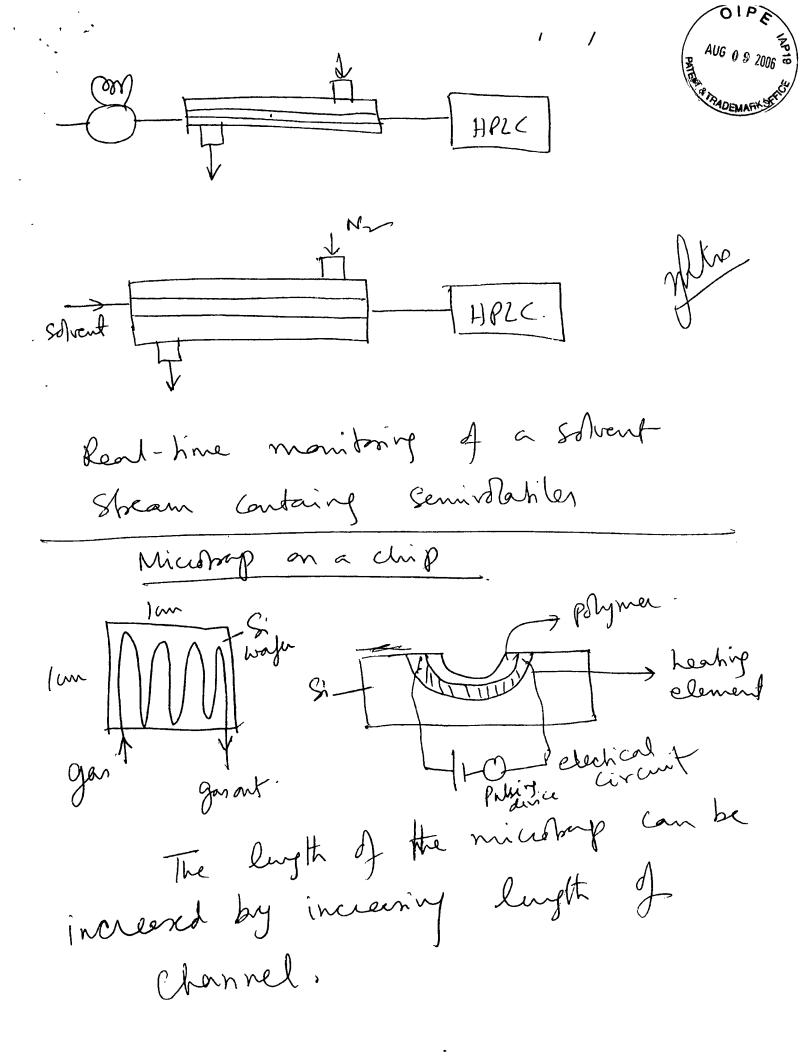
Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## **DECLARATION UNDER 37 CFR §1.131**

- I, Somenath Mitra, do hereby declare and say:
- 1. I am a named inventor of the above-captioned patent application.
- I conceived the idea and fully documented my conception at least as early as June 1998.
   Attached are pages from my lab notebook which were generated in or around 1998.
- 3. The lab notebook pages describe a microheater comprising at least one microchannel formed on a substrate and a conductor disposed in the at least one microchannel.
- 4. From the time I conceived the invention until the time the patent application was filed I worked diligently on the completion of the invention.
- 5. I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and that these statements were made with the knowledge that willful false statements and the likes so made are punishable by fine or imprisonment, or both under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patents issuing thereon.

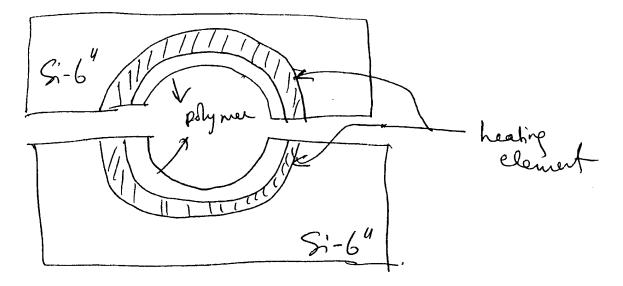
Somenath Mitra

Date: 8 5 , 200



The heating element can be a layer of metal or Delectrical heating paint, like the men we used before from ando stores.

Two mirror images can be put on sop of each other



or Si-6" Si-12/98

m chip-6/25/98 Si water 1111), mak, 2 thoughy Etch. T etch channel. spin coat

hearting film

of carducting polymen. ar Implant or sputter a metal. > Spin coat polymen or deposit by other Band mirror inofes

6/27/98 rd Mgi all a ne wafer 1 cm Senser Senser Schimn GC cohumn 2 cm Same architechne, 1st device un microhap, second as G(commn, Sensor as detector. Micosop - high capacity, pulsed operation Ge Column - Low capacity, heat by temperature programming. Increase coment slowly through the conductive layer, leading to temperature ramp.

Michael & Column an Ling section for the

The heating clement & polymers are different in the two sections. In the first section it a high copacity phymen that retains strongly In the latter section its a GC, so, low capacity. Healing for the first section for injection/pulsity. The latter such in for slow heating & temperature of Sills with.